

PRODUCT NUMBER	PCB THICKNESS	DIM "A"
88945-X02	1.6	2.73
88945-X12	2.4	3.53
88945-X02LF	1.6	2.73
88945-X12LF	2.4	3.53

PLATING IN CONTACT AREA		
PLATING CODE	THICKNESS	UNDERPLATING
88945-1Y2	0.8 μm GOLD	1.3 μm Ni MIN.
-2Y2	2.0 μm GOLD	1.3 μm Ni MIN.
-3Y2	1.3 μm GOLD	1.3 μm Ni MIN.
-9Y2	0.8 μm GXT	1.3 μm Ni MIN.
-1Y2LF	0.8 μm GOLD	1.3 μm Ni MIN.
-2Y2LF	2.0 μm GOLD	1.3 μm Ni MIN.
-3Y2LF	1.3 μm GOLD	1.3 μm Ni MIN.
88945-9Y2LF	0.8 μm GXT	1.3 μm Ni MIN.

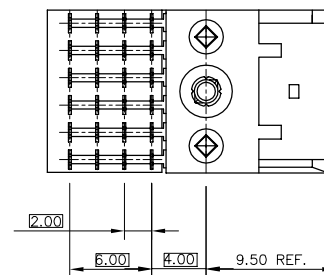
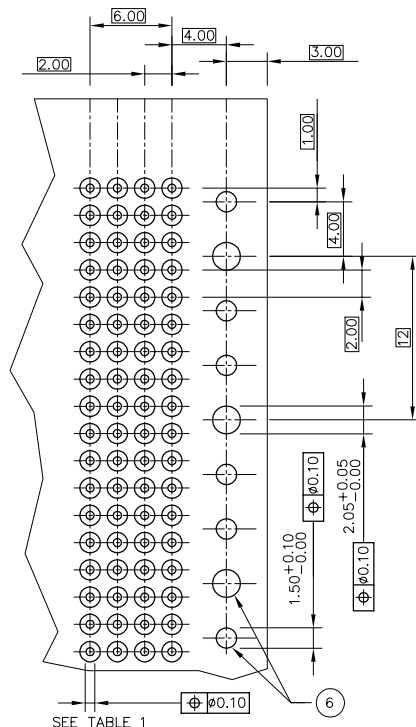
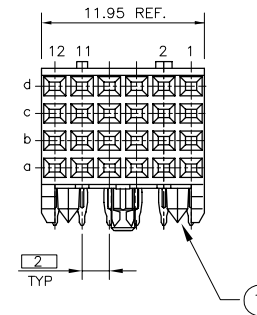
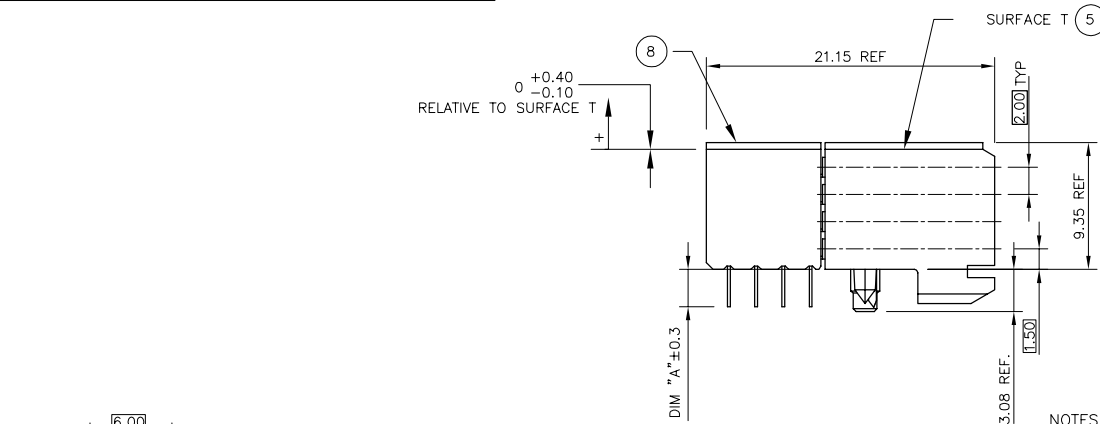


TABLE 1	
PLATED THRU HOLE REQUIREMENTS	
HOLE DIAMETER AFTER PLATING	0.65-0.80
DRILLED HOLE	0.81-0.86 (0.85 DRILL)
COPPER PLATING	0.025 - 0.05
SnPb PLATING	0.005-0.015

RECOMMENDED PC BOARD LAYOUT,
COMPONENT SIDE.

NOTES:

- ① CONNECTOR MATERIALS:
HOUSING: LCP, 30% GLASS FILLED,
UL 94-V0 COMPLIANT
TERMINAL: PHOSPHOR BRONZE ALLOY
2. PRESS-FIT TAIL PLATING: 0.5-1.5 μ m TIN LEAD
3. PRODUCT SPECIFICATION:
GS-12-002
4. APPLICATION SPECIFICATIONS:
BUS-20-060
GS-20-001
TA-941
- ⑤ PRODUCT MARKING: (PART NUMBER & LOT CODE).
- ⑥ INDICATED HOLES ARE UNPLATED.
- ⑦ LOCATION PEG FEATURES MAY NOT BE AVAILABLE AS SHOWN.
- ⑧ TOP SURFACE OF PRESS BLOCK MAY EXTEND UP TO 0.4MM HIGHER THAN HOUSING. THIS MAY AFFECT THE TAIL LENGTH BEFORE APPLICATION TO A BOARD.
9. THESE PRODUCTS WHERE THE PART NUMBER ENDS IN "LF" MEET THE EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.

ALL PRODUCTS WILL WITHSTAND EXPOSURE TO 240°C FOR 60 SECONDS IN A CONVECTION, INFR-RED OR VAPOR PHASE REFLOW OVEN.
10. FOR LEAD FREE PART NUMBERS ADD "LF" SUFFIX. EXAMPLE: 88945-XXYLF.

[illegible]